Resonant Switching Series

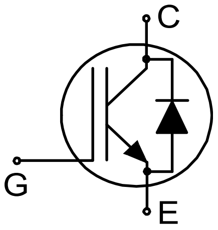
Reverse conducting IGBT with monolithic body diode

IHW50N65R5

Data sheet

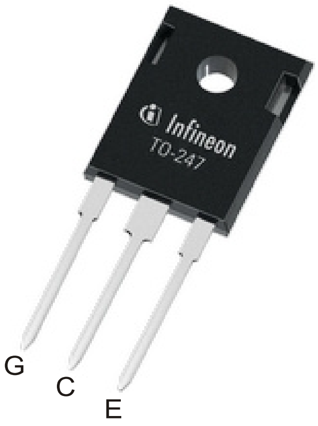
Industrial Power Control

Reverse conducting IGBT with monolithic body diode



Features:

- Powerful monolithic reverse-conducting diode with low forward voltage
- TRENCHSTOP^{TM} technology offers:
- very tight parameter distribution
- high ruggedness and stable temperature behavior
- very low V_{CEsat} and low E_{off}
- easy parallel switching capability due to positive temperature coefficient in V_{CEsat}
- Low EMI
- Qualified according to JESD-022 for target applications
- Pb-free lead plating; RoHS compliant
- Complete product spectrum and PSpice Models: http://www.infineon.com/igbt/



Applications:

- Induction cooking
- Inverterized microwave ovens
- Resonant converters

Key Performance and Package Parameters

Type	V_{CE}	I_C	V_{CEsat}, T_{vj}=25°C	T_{vjmax}	Marking	Package
IHW50N65R5	650V	50A	1.35V	175°C	H50ER5	PG-TO247-3

Table of Contents

Maximum Ratings

For optimum lifetime and reliability, Infineon recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

Parameter	Symbol	Value	Unit
Collector-emitter voltage, $T_{vj} \geq 25°C$	V_{CE}	650	V
DC collector current, limited by T_{vjmax} $T_C = 25°C$ value limited by bondwire $T_C = 100°C$	I_C	80.0 50.0	A
Pulsed collector current, t_p limited by T_{vjmax}	I_{Cpuls}	150.0	A
Turn off safe operating area $V_{CE} \leq 650V$, $T_{vj} \leq 175°C$, $t_p = 1µs$	-	150.0	A
Diode forward current, limited by T_{vjmax} $T_C = 25°C$ value limited by bondwire $T_C = 100°C$	I_F	37.0 22.0	A
Diode pulsed current, t_p limited by T_{vjmax}	I_{Fpuls}	150.0	A
Gate-emitter voltage	V_{GE}	±20	V
Power dissipation $T_C = 25°C$ Power dissipation $T_C = 100°C$	P_{tot}	282.0 141.0	W
Operating junction temperature	T_{vj}	-40...+175	°C
Storage temperature	T_{stg}	-55...+150	°C
Soldering temperature, wave soldering 1.6mm (0.063in.) from case for 10s		260	°C
Mounting torque, M3 screw Maximum of mounting processes: 3	M	0.6	Nm

Thermal Resistance

Parameter	Symbol	Conditions	Max. Value	Unit
Characteristic				
IGBT thermal resistance, junction - case	$R_{th(j-c)}$		0.53	K/W
Diode thermal resistance, junction - case	$R_{th(j-c)}$		2.29	K/W
Thermal resistance junction - ambient	$R_{th(j-a)}$		40	K/W

Electrical Characteristic, at T_{vj} = 25°C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	V_{GE} = 0V, I_C = 0.20mA	650	-	-	V
Collector-emitter saturation voltage	V_{CEsat}	V_{GE} = 15.0V, I_C = 50.0A T_{vj} = 25°C T_{vj} = 175°C	- -	1.35 1.60	1.70 -	V
Diode forward voltage	V_F	V_{GE} = 0V, I_F = 50.0A T_{vj} = 25°C T_{vj} = 175°C	- -	1.70 2.00	2.10 -	V
Gate-emitter threshold voltage	$V_{GE(th)}$	I_C = 0.50mA, V_{CE} = V_{GE}	3.2	4.0	4.8	V
Zero gate voltage collector current	I_{CES}	V_{CE} = 650V, V_{GE} = 0V T_{vj} = 25°C T_{vj} = 175°C	- -	- 1250	40 -	µA
Gate-emitter leakage current	I_{GES}	V_{CE} = 0V, V_{GE} = 20V	-	-	100	nA
Transconductance	g_{fs}	V_{CE} = 20V, I_C = 50.0A	-	120.0	-	S
Integrated gate resistor	r_G			none		Ω

Electrical Characteristic, at T_{vj} = 25°C, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Dynamic Characteristic						
Input capacitance	C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz	-	6140	-	pF
Output capacitance	C_{oes}		-	55	-	
Reverse transfer capacitance	C_{res}		-	23	-	
Gate charge	Q_G	V_{CC} = 480V, I_C = 50.0A, V_{GE} = 15V	-	230.0	-	nC
Internal emitter inductance measured 5mm (0.197 in.) from case	L_E		-	13.0	-	nH

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic, at T_{vj} = 25°C						
Turn-on delay time	$t_{d(on)}$	T_{vj} = 25°C, V_{CC} = 400V, I_C = 50.0A, V_{GE} = 0.0/15.0V, $R_{G(on)}$ = 8.0Ω, $R_{G(off)}$ = 8.0Ω, $L\sigma$ = 45nH, $C\sigma$ = 32pF $L\sigma$, $C\sigma$ from Fig. E Energy losses include “tail” and diode reverse recovery.	-	30	-	ns
Rise time	t_r		-	20	-	ns
Turn-off delay time	$t_{d(off)}$		-	210	-	ns
Fall time	t_f		-	8	-	ns
Turn-on energy	E_{on}		-	1.50	-	mJ
Turn-off energy	E_{off}		-	0.45	-	mJ
Total switching energy	E_{ts}		-	1.95	-	mJ

Diode Characteristic, at T_{vj} = 25°C

Diode reverse recovery time	t_{rr}	T_{vj} = 25°C, V_R = 400V, I_F = 50.0A, di_F/dt = 1100A/µs	-	137	-	ns
Diode reverse recovery charge	Q_{rr}		-	2.75	-	µC
Diode peak reverse recovery current	I_{rrm}		-	37.0	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	-1100	-	A/µs

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic, at T_{vj} = 175°C						
Turn-on delay time	$t_{d(on)}$	T_{vj} = 175°C, V_{CC} = 400V, I_C = 50.0A, V_{GE} = 0.0/15.0V, $R_{G(on)}$ = 8.0Ω, $R_{G(off)}$ = 8.0Ω, $L\sigma$ = 45nH, $C\sigma$ = 32pF $L\sigma$, $C\sigma$ from Fig. E Energy losses include “tail” and diode reverse recovery.	-	29	-	ns
Rise time	t_r		-	22	-	ns
Turn-off delay time	$t_{d(off)}$		-	240	-	ns
Fall time	t_f		-	21	-	ns
Turn-on energy	E_{on}		-	1.76	-	mJ
Turn-off energy	E_{off}		-	0.73	-	mJ
Total switching energy	E_{ts}		-	2.49	-	mJ

Diode Characteristic, at T_{vj} = 175°C

Diode reverse recovery time	t_{rr}	T_{vj} = 175°C, V_R = 400V, I_F = 50.0A, di_F/dt = 1100A/µs	-	145	-	ns
Diode reverse recovery charge	Q_{rr}		-	5.45	-	µC
Diode peak reverse recovery current	I_{rrm}		-	60.0	-	A
Diode peak rate of fall of reverse recovery current during t_b	di_{rr}/dt		-	-2050	-	A/µs

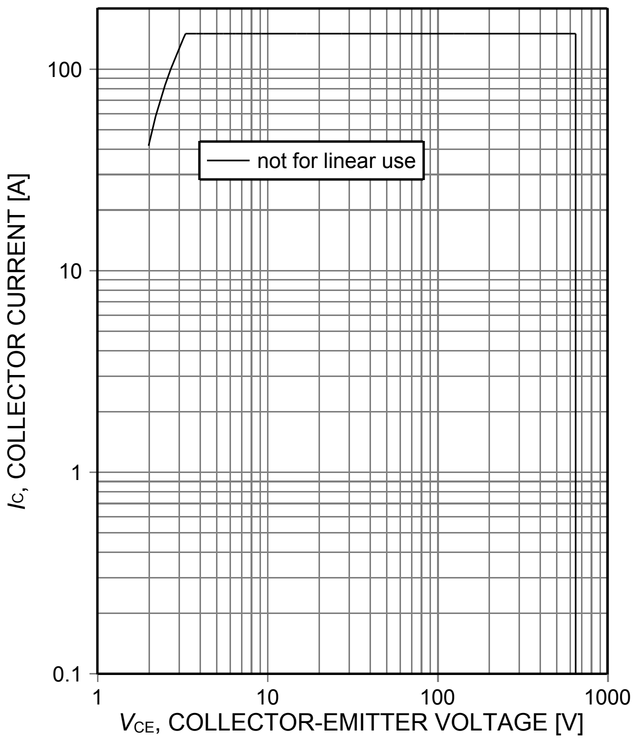


Figure 1. **Safe operating area**
(D=0, T_C=25°C, T_{vj}≤175°C, V_{GE}=15V, t_p=1μs)

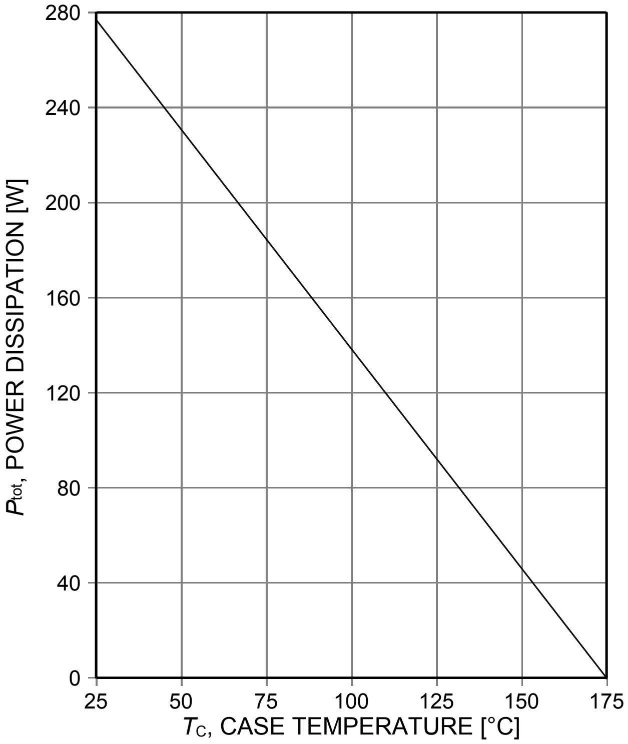


Figure 2. **Power dissipation as a function of case temperature**
(T_{vj}≤175°C)

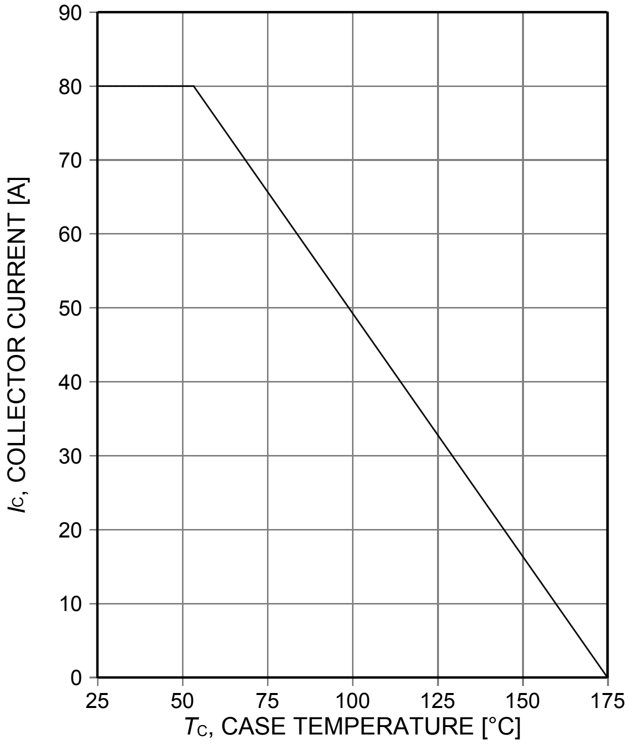


Figure 3. **Collector current as a function of case temperature**
(V_{GE}≥15V, T_{vj}≤175°C)

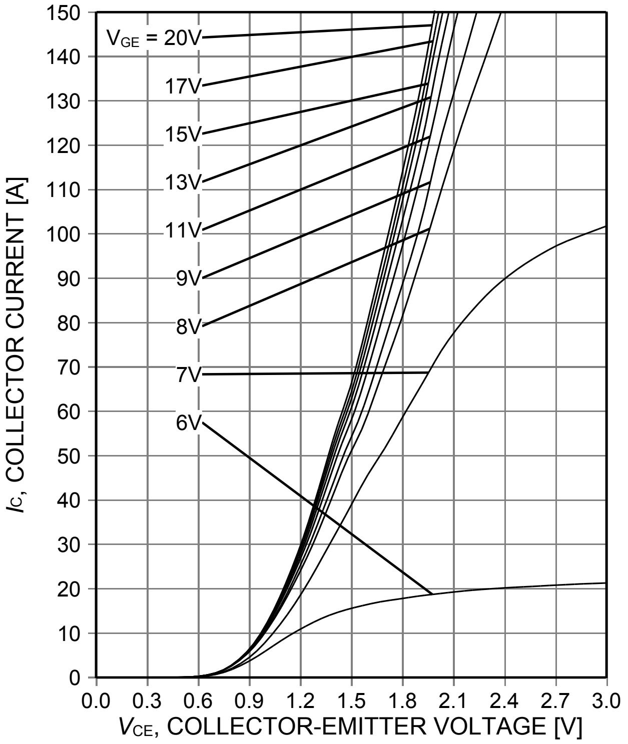


Figure 4. **Typical output characteristic**
(T_{vj}=25°C)

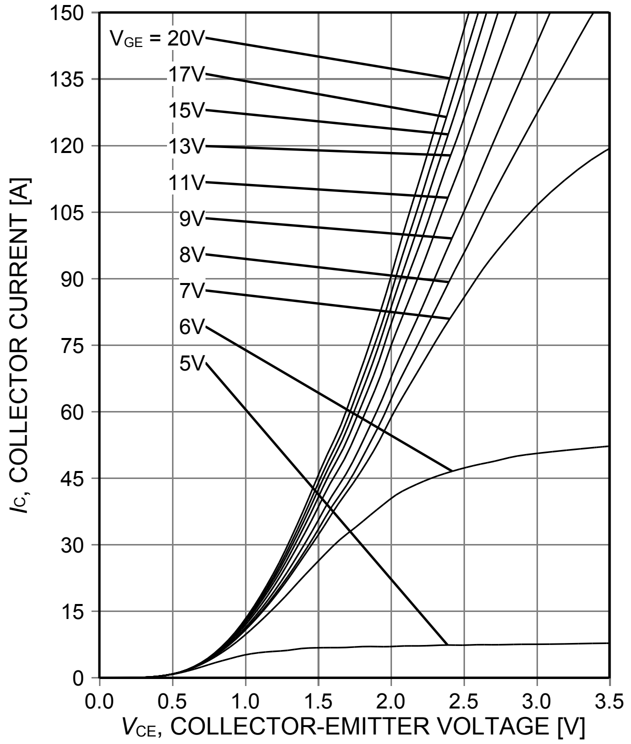


Figure 5. **Typical output characteristic**
(T_{vj}=175°C)

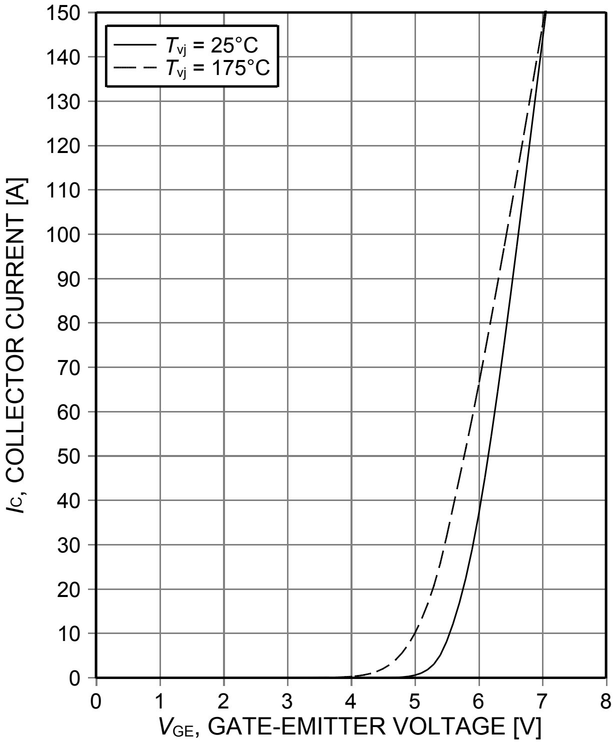


Figure 6. **Typical transfer characteristic**
(V_{CE}=20V)

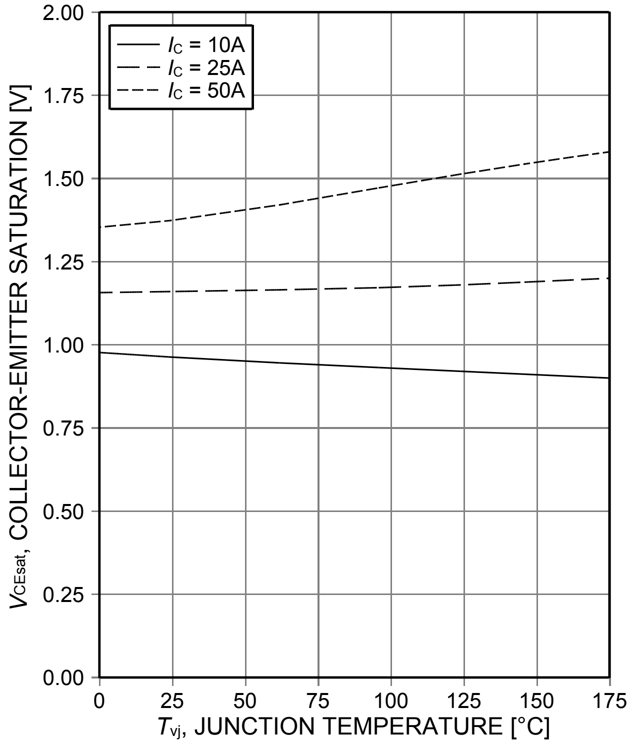


Figure 7. **Typical collector-emitter saturation voltage as a function of junction temperature**
(V_{GE}=15V)

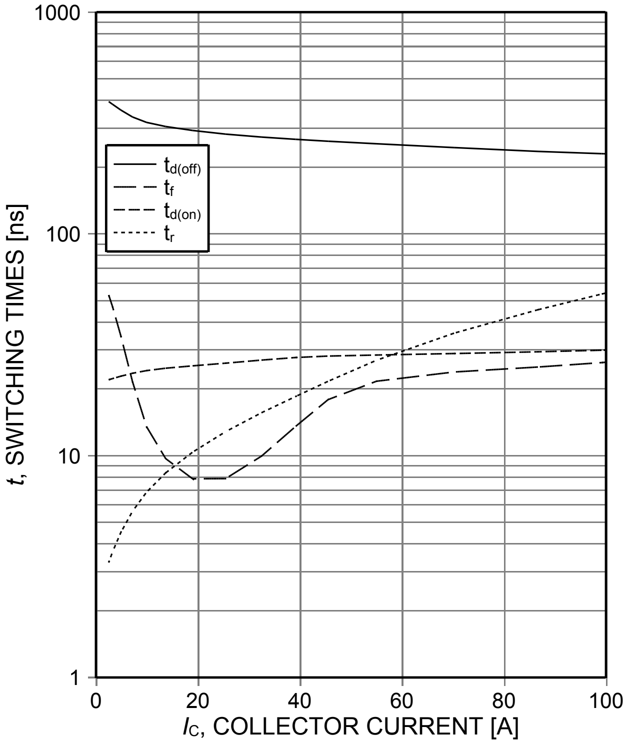


Figure 8. **Typical switching times as a function of collector current**
(inductive load, T_{vj}=175°C, V_{CE}=400V, V_{GE}=0/15V, $R_{G(on)}$=8Ω, $R_{G(off)}$=8Ω, dynamic test circuit in Figure E)

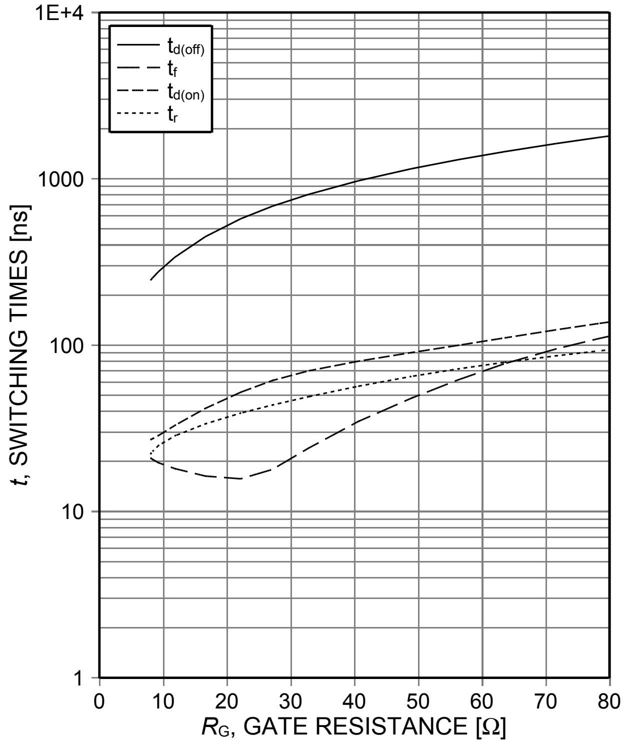


Figure 9. **Typical switching times as a function of gate resistance**
(inductive load, T_{vj}=175°C, V_{CE}=400V, V_{GE}=0/15V, I_C=50A, dynamic test circuit in Figure E)

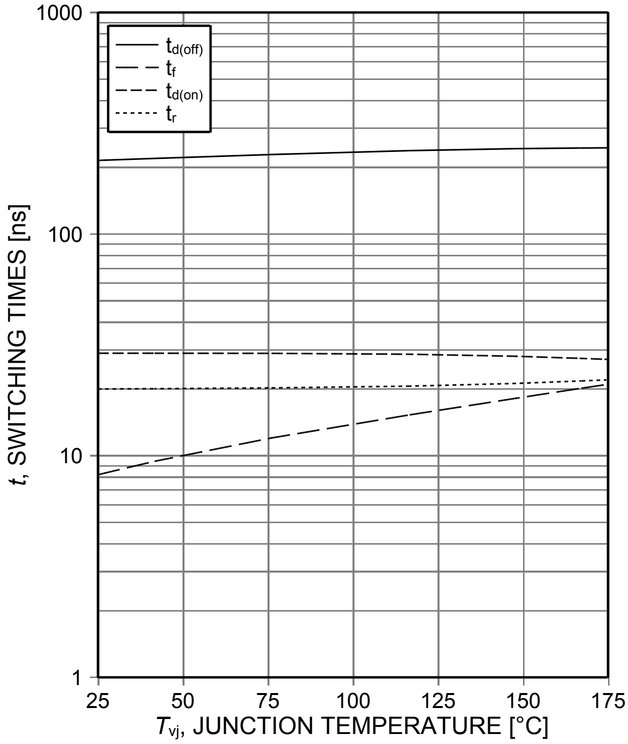


Figure 10. **Typical switching times as a function of junction temperature**
(inductive load, V_{CE}=400V, V_{GE}=0/15V, I_C=50A, $R_{G(on)}$=8Ω, $R_{G(off)}$=8Ω, dynamic test circuit in Figure E)

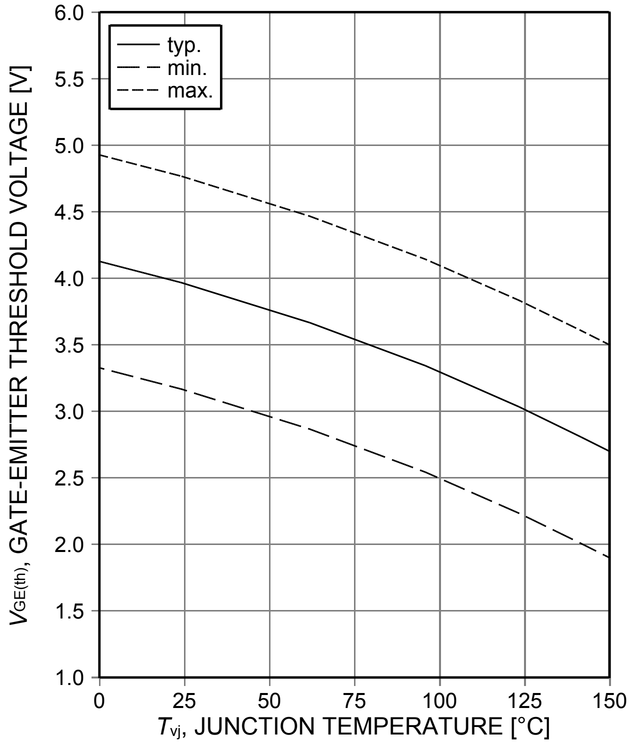


Figure 11. **Gate-emitter threshold voltage as a function of junction temperature**
(I_C=0.5mA)

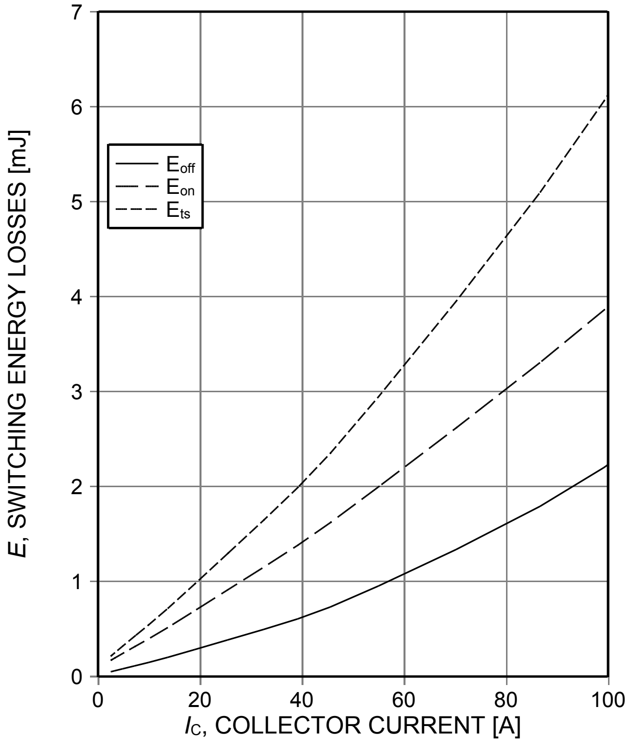


Figure 12. **Typical switching energy losses as a function of collector current**
(inductive load, T_{vj}=175°C, V_{CE}=400V, V_{GE}=0/15V, $R_{G(on)}$=8Ω, $R_{G(off)}$=8Ω, dynamic test circuit in Figure E)

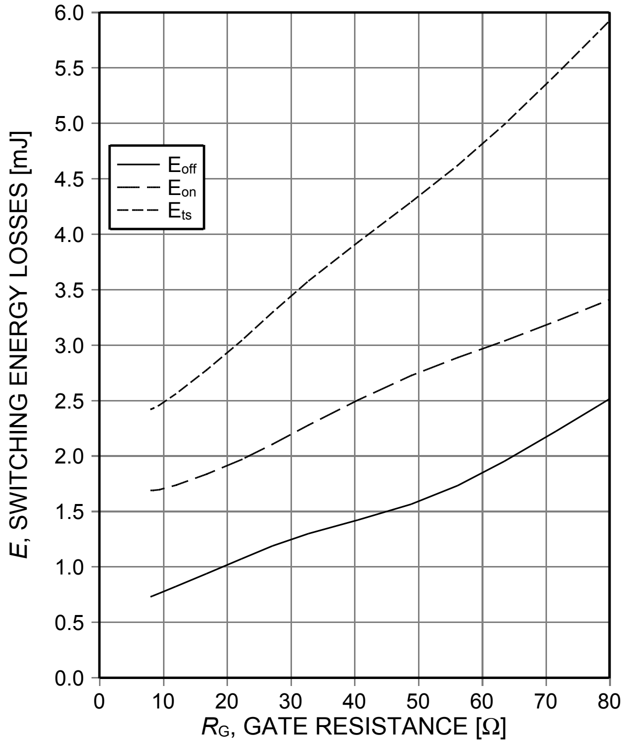


Figure 13. **Typical switching energy losses as a function of gate resistance**
(inductive load, T_{vj}=175°C, V_{CE}=400V, V_{GE}=0/15V, I_C=50A, dynamic test circuit in Figure E)

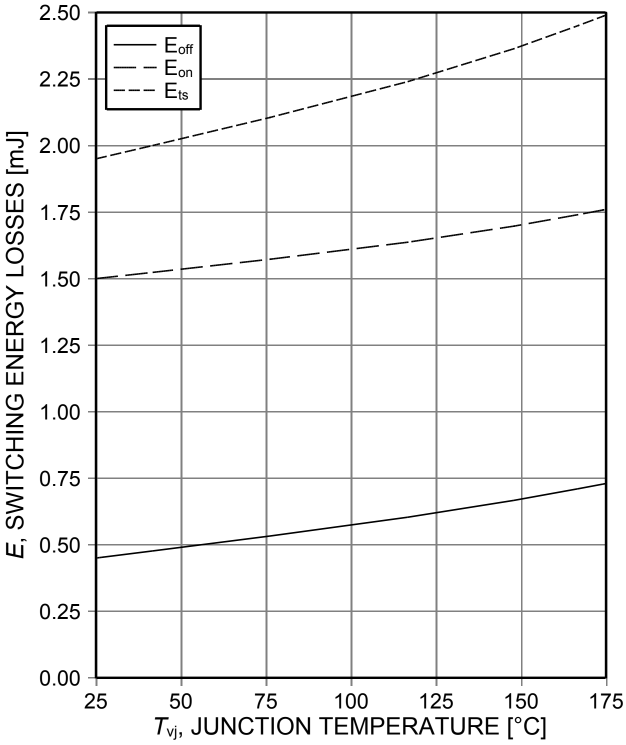


Figure 14. **Typical switching energy losses as a function of junction temperature**
(inductive load, V_{CE}=400V, V_{GE}=0/15V, I_C=50A, $R_{G(on)}$=8Ω, $R_{G(off)}$=8Ω, dynamic test circuit in Figure E)

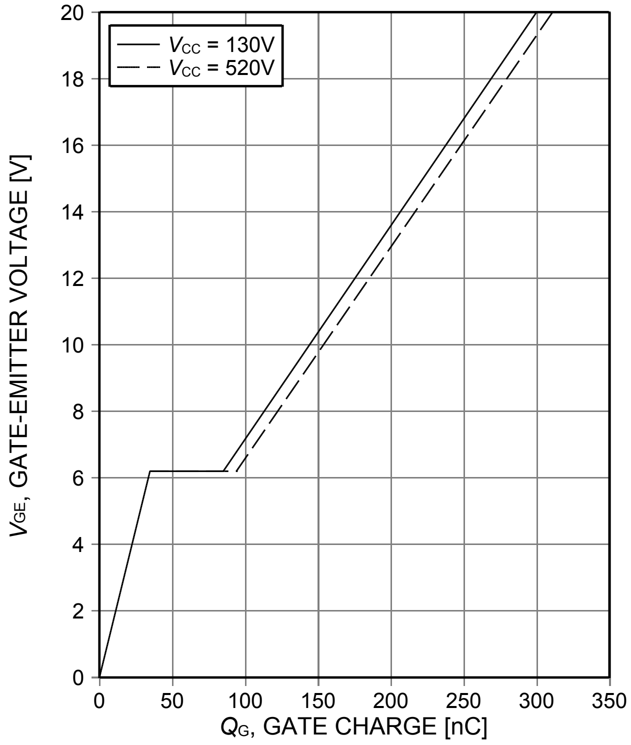


Figure 15. **Typical gate charge**
(I_C=50A)

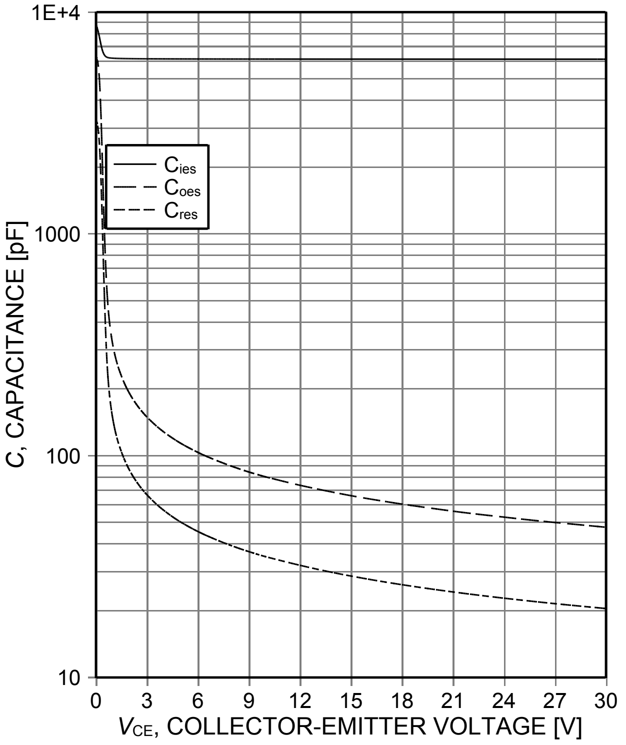
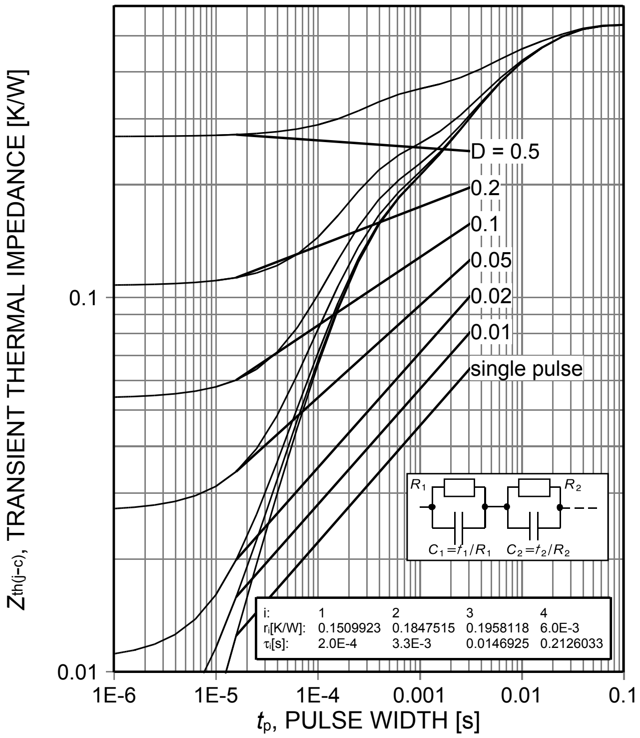
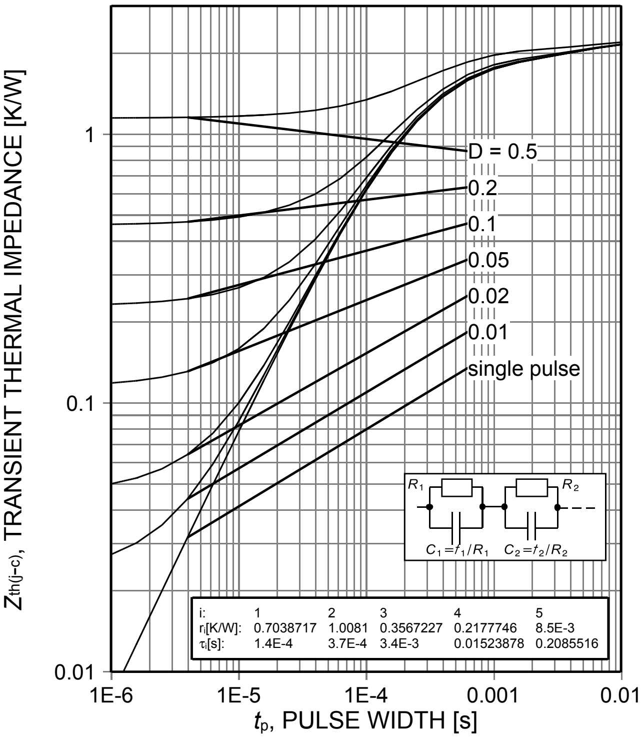


Figure 16. **Typical capacitance as a function of collector-emitter voltage**
(V_{GE}=0V, f=1MHz)



i:	1	2	3	4
r_i[K/W]:	0.1509923	0.1847515	0.1958118	6.0E-3
τ_i[s]:	2.0E-4	3.3E-3	0.0146925	0.2126033

Figure 17. **IGBT transient thermal impedance as a function of pulse width**
($D = t_p/T$)



i:	1	2	3	4	5
r_i[K/W]:	0.7038717	1.0081	0.3567227	0.2177746	8.5E-3
τ_i[s]:	1.4E-4	3.7E-4	3.4E-3	0.01523878	0.2085516

Figure 18. **Diode transient thermal impedance as a function of pulse width**
($D = t_p/T$)

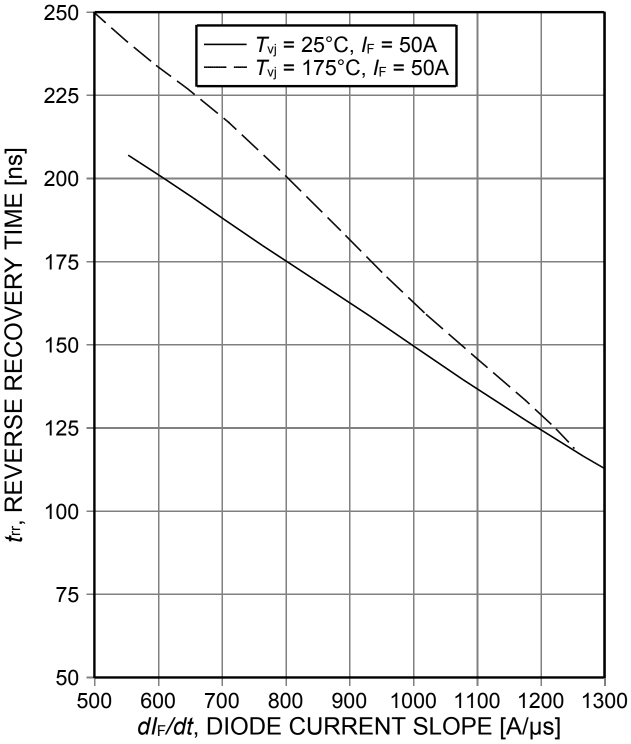


Figure 19. **Typical reverse recovery time as a function of diode current slope**
(V_R=400V)

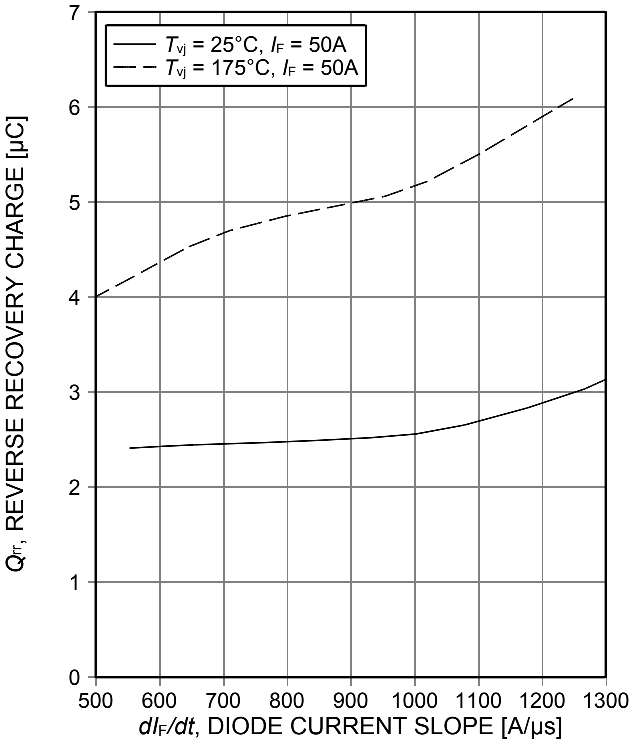


Figure 20. **Typical reverse recovery charge as a function of diode current slope**
(V_R=400V)

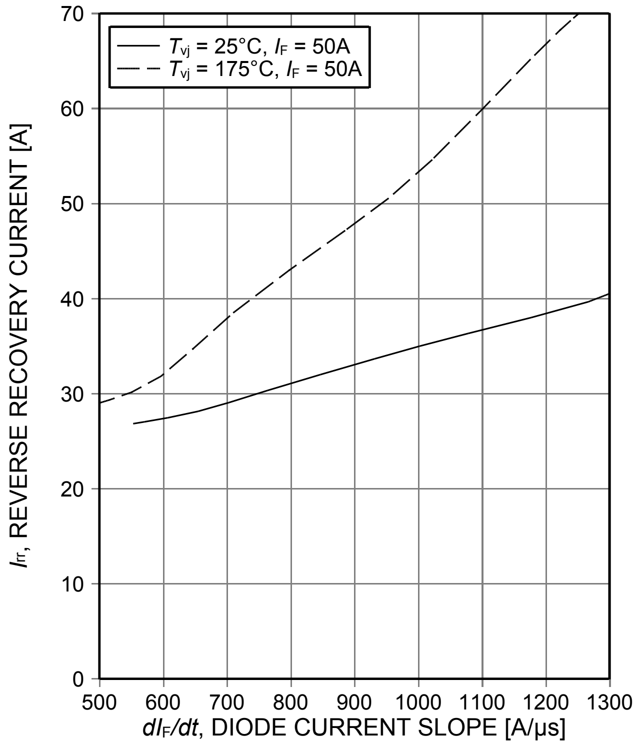


Figure 21. **Typical reverse recovery current as a function of diode current slope**
(V_R=400V)

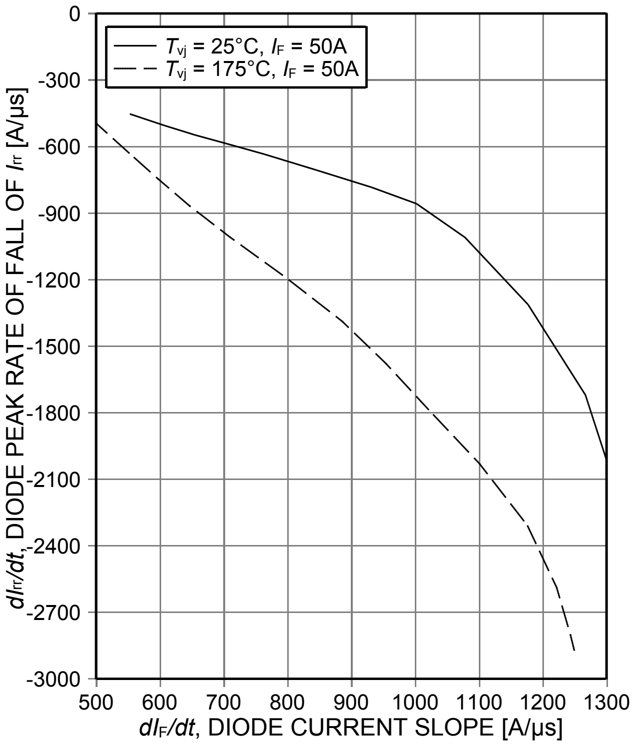


Figure 22. **Typical diode peak rate of fall of reverse recovery current as a function of diode current slope**
(V_R=400V)

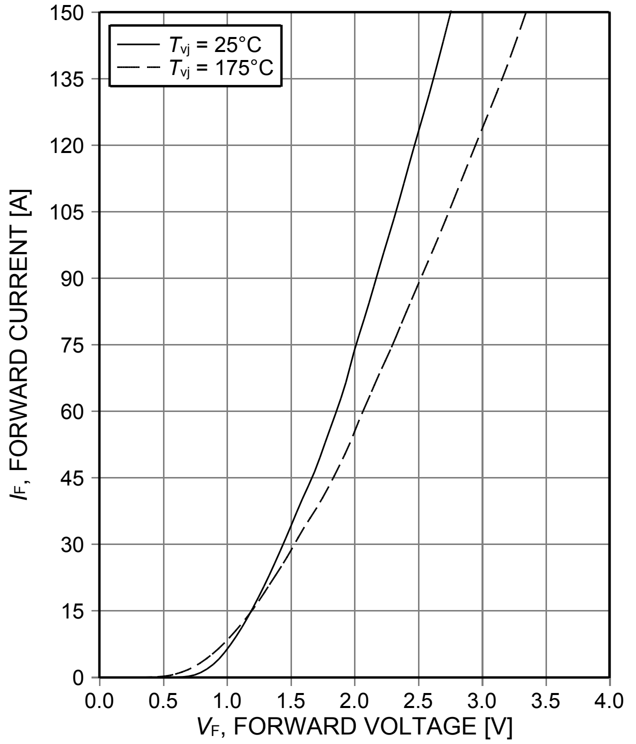


Figure 23. **Typical diode forward current as a function of forward voltage**

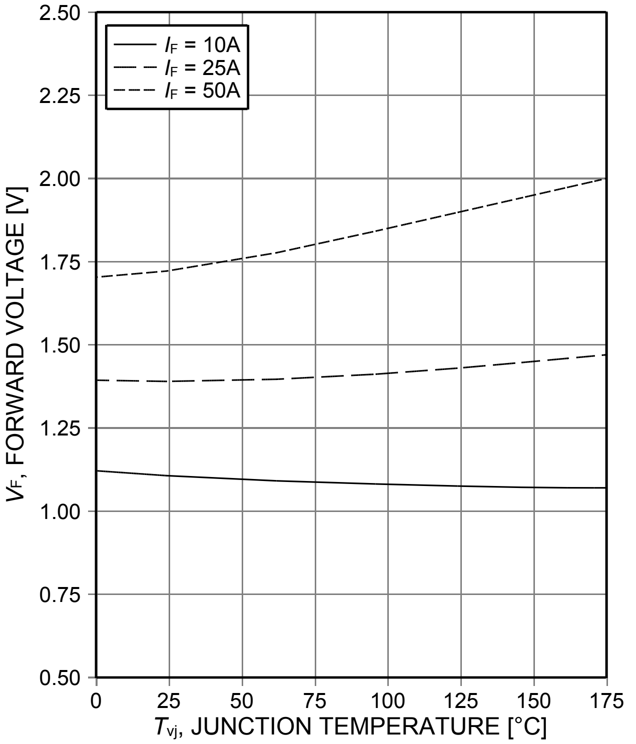
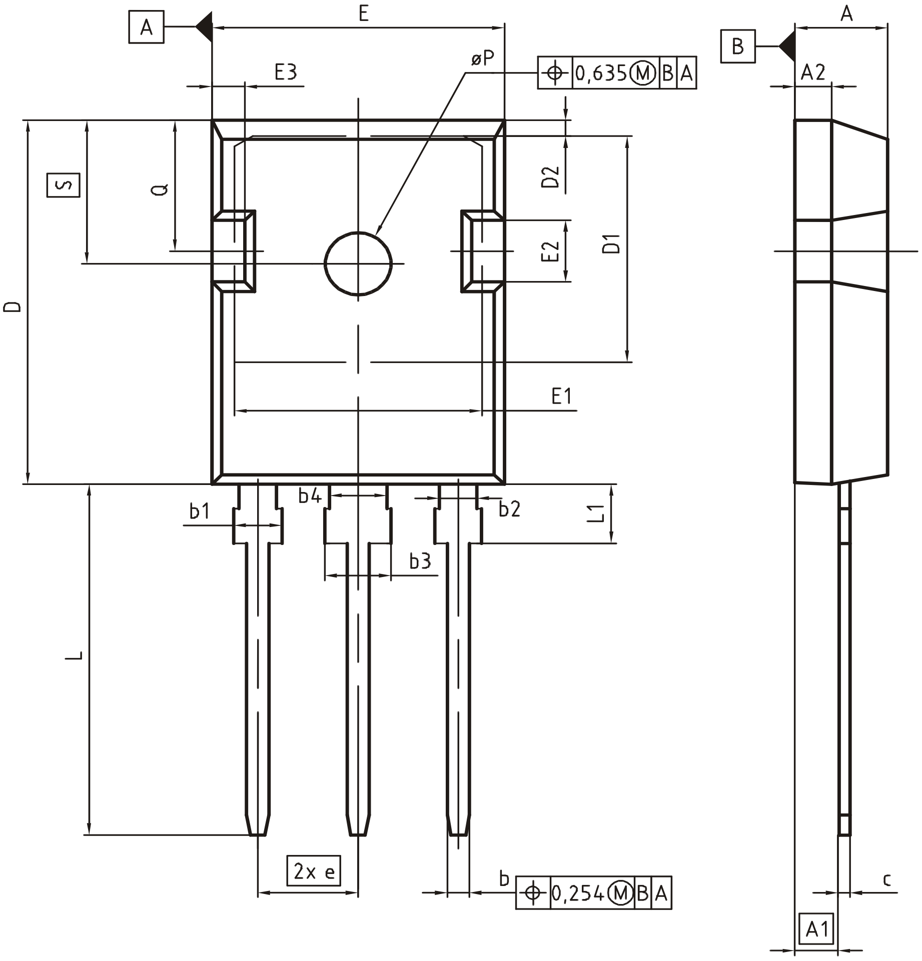


Figure 24. **Typical diode forward voltage as a function of junction temperature**

Package Drawing PG-TO247-3



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.27	2.54	0.089	0.100
A2	1.85	2.16	0.073	0.085
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	5.44 (BSC)		0.214 (BSC)	
N	3		3	
L	19.80	20.32	0.780	0.800
L1	4.10	4.47	0.161	0.176
øP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

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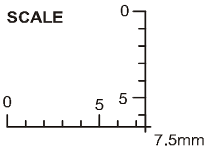
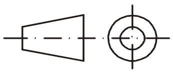
SCALE



EUROPEAN PROJECTION



ISSUE DATE
09-07-2010

REVISION
05

Testing Conditions

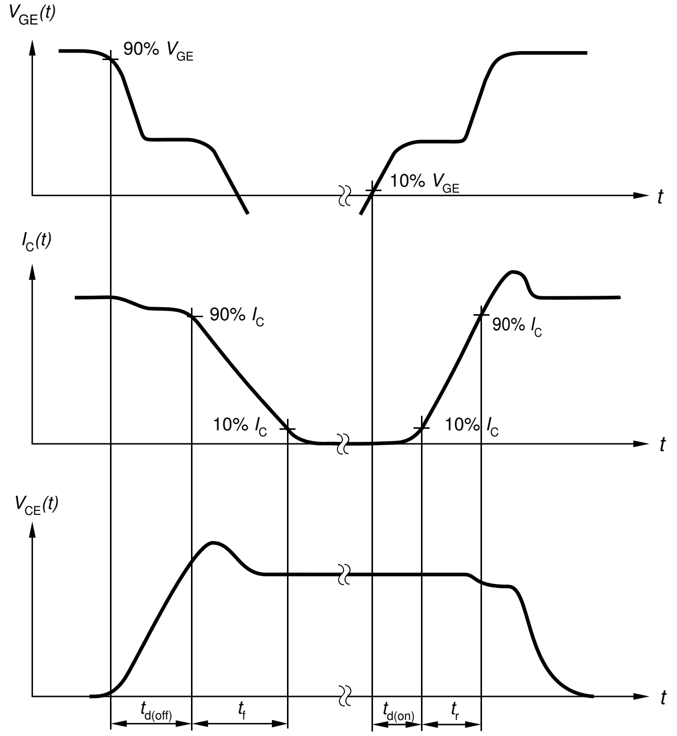


Figure A. **Definition of switching times**

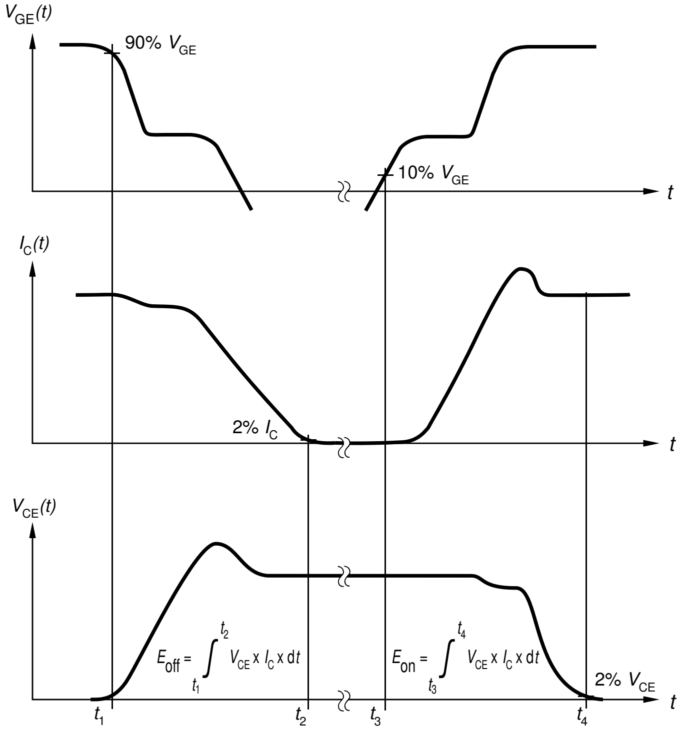


Figure B. **Definition of switching losses**

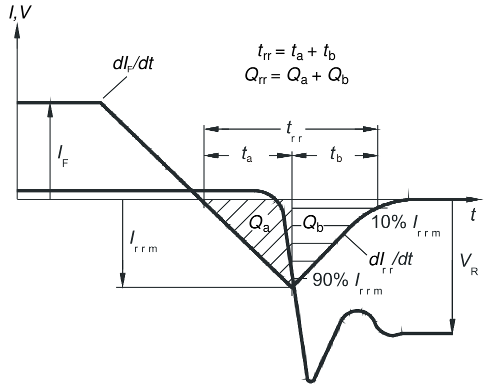


Figure C. **Definition of diode switching characteristics**

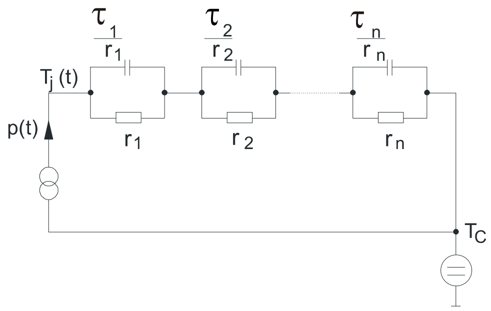


Figure D. **Thermal equivalent circuit**

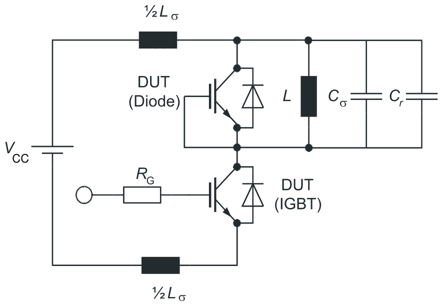


Figure E. **Dynamic test circuit**
Parasitic inductance L_σ,
parasitic capacitor C_σ,
relief capacitor C_r,
(only for ZVT switching)

Revision History

IHW50N65R5

Revision: 2015-12-18, Rev. 2.4

Previous Revision

Revision	Date	Subjects (major changes since last revision)
1.1	2014-06-13	Preliminary data sheet
1.2	2014-06-16	-
2.1	2014-09-12	Final data sheet
2.2	2014-11-27	Update of diode forward current values
2.3	2014-12-16	Update Fig.14 E_{on}, E_{off} at 25°C
2.4	2015-12-18	Minor change Conditions Static Characteristic

Published by
Infineon Technologies AG
81726 München, Germany

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For further information on the product, technology, delivery terms and conditions and prices please contact your nearest Infineon Technologies office (www.infineon.com).

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Warnings
Due to technical requirements products may contain dangerous substances. For information on the types in question please contact your nearest Infineon Technologies office.

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LifeElectronics
Живое партнерство

ООО "ЛайфЭлектроникс" **"LifeElectronics" LLC**

ИНН 7805602321 КПП 780501001 Р/С 40702810122510004610 ФАКБ "АБСОЛЮТ БАНК" (ЗАО) в г.Санкт-Петербурге К/С 30101810900000000703 БИК 044030703

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- *Конкурентоспособные цены и скидки постоянным клиентам.*
- *Специальные условия для постоянных клиентов.*
- *Подбор аналогов.*
- *Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.*

- *Приемлемые сроки поставки, возможна ускоренная поставка.*
- *Доставку товара в любую точку России и стран СНГ.*
- *Комплексную поставку.*
- *Работу по проектам и поставку образцов.*
- *Формирование склада под заказчика.*

- *Сертификаты соответствия на поставляемую продукцию (по желанию клиента).*
- *Тестирование поставляемой продукции.*
- *Поставку компонентов, требующих военную и космическую приемку.*
- *Входной контроль качества.*
- *Наличие сертификата ISO.*

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- *Регистрацию проекта у производителя компонентов.*
- *Техническую поддержку проекта.*
- *Защиту от снятия компонента с производства.*
- *Оценку стоимости проекта по компонентам.*
- *Изготовление тестовой платы монтаж и пусконаладочные работы.*

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